LMH6611,LMH6612

LMH6611/LMH6612 Single Supply 345 MHz Rail-to-Rail Output Amplifiers

Literature Number: SNOSB00H

LMH6611/LMH6612

Single Supply 345 MHz Rail-to-Rail Output Amplifiers

General Description

The LMH6611 (single, with shutdown) and LMH6612 (dual) are 345 MHz rail-to-rail output amplifiers consuming just 3.2 mA of quiescent current per channel and designed to deliver high performance in power conscious single supply systems. The LMH6611 and LMH6612 have precision trimmed input offset voltages with low noise and low distortion performance as required for high accuracy video, test and measurement, and communication applications. The LMH6611 and LMH6612 are members of the PowerWise family and have an exceptional power-to-performance ratio.

With a trimmed input offset voltage of 0.022 mV and a high open loop gain of 103 dB the LMH6611 and LMH6612 meet the requirements of DC sensitive high speed applications such as low pass filtering in baseband I and Q radio channels. These specifications combined with a 0.01% settling time of 100 ns, a low noise of 10 nV/ \sqrt{Hz} and better than 102 dBc SFDR at 100 kHz make these amplifiers particularly suited to driving 10, 12 and 14-bit high speed ADCs. The 45 MHz 0.1 dB bandwidth (A_V = 2) driving 2 V_{PP} into 150Ω allows the amplifiers to be used as output drivers in 1080i and 720p HDTV applications.

The input common mode range extends from 200 mV below the negative supply rail up to 1.2V from the positive rail. On a single 5V supply with a ground terminated 150Ω load the output swings to within 49 mV of the ground, while a mid-rail terminated 1 kΩ load will swing to 77 mV of either rail.

The amplifiers will operate on a 2.7V to 11V single supply or $±1.35V$ to $±5.5V$ split supply. The LMH6611 single is available in 6-Pin TSOT23 and has an independent active low disable pin which reduces the supply current to 120 µA. The LMH6612 is available in 8-Pin SOIC. Both the LMH6611 and LMH6612 are available in −40°C to +125°C extended industrial temperature grade.

Features

 V_S = 5V, R_L = 1 kΩ, T_A = 25°C and A_V = +1, unless otherwise specified.

- Operating voltage range 2.7V to 11V
■ Supply current per channel 3.2 mA Supply current per channel 3.2 mA

Small signal bandwidth 345 MHz ■ Small signal bandwidth 345 MHz
■ Open loop qain ■ Open loop gain 103 dB
■ Input offset voltage (limit at 25°C)
■ to 750 mV Input offset voltage (limit at 25° C)
-
- Slew rate 460 V/µs

0.1 dB bandwidth 45 MHz
- 0.1 dB bandwidth 45 MHz
■ Settling time to 0.1% 45 MHz
- Settling time to 0.1% 67 ns
Settling time to 0.01% 67 ns
- Settling time to 0.01% 100 ns
■ SFDR (f = 100 kHz, A_v = 2, V_{OUT} = 2 V_{PD}) 102 dBc ■ SFDR (f = 100 kHz, A_V = 2, V_{OUT} = 2 V_{PP}) 102 dBc
- Low voltage noise 10 nV/√Hz
Output current the total state 100 mA
- Output current
■ CMVB
- - Rail-to-Rail output
	- -40° C to +125°C temperature range

Applications

- ADC driver
- DAC buffer
- Active filters
- High speed sensor amplifier
- Current sense amplifier
- 1080i and 720p analog video amplifier
- STB, TV video amplifier
- Video switching and muxing

-0.2V to 3.8V

Absolute Maximum Ratings (*[Note 1](#page-8-0)*)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage $(V_S = V^+ - V^-)$ 12V Junction Temperature (*[Note 3](#page-8-0)*) 150°C max

Operating Ratings (*[Note 1](#page-8-0)*)

+3V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for T_J = +25°C, V+ = 3V, V− = 0V, V_S = V+ – V−, DISABLE = 3V, V_{CM} = V_O = V+/2, A_V = +1, R_F = 0Ω, when A_V ≠ +1 then R_F = 560Ω, R_L = 1 kΩ. **Boldface** limits apply at temperature extremes. (*[Note 4](#page-8-0)*)

+5V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for T_J = +25°C, V+ = 5V, V- = 0V, V_S = V+ – V-, DISABLE = 5V, V_{CM} = V_O = $V+/2$, A_V = +1, R_F = 0Ω, when A_V ≠ +1 then R_F = 560Ω, R_L = 1 kΩ. **Boldface** limits apply at temperature extremes.

LMH6611/LMH6612 **LMH6611/LMH6612**

±5V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for T_J = +25°C, V+ = 5V, V- = -5V, V_S = V+ - V-, DISABLE = 5V, V_{CM} = V_O = $0V$, A_V = +1, R_F = 0Ω, when A_V ≠ +1 then R_F = 560Ω, R_L = 1 kΩ. **Boldface** limits apply at temperature extremes.

LMH6611/LMH6612 **LMH6611/LMH6612**

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics. **Note 2:** Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).

Note 3: The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is

 $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$. All numbers apply for packages soldered directly onto a PC Board.

Note 4: Boldface limits apply to temperature range of −40°C to 125°C

Note 5: Voltage average drift is determined by dividing the change in V_{OS} by temperature change.

Note 6: Do not short circuit the output. Continuous source or sink currents larger than the I_{OUT} typical are not recommended as they may damage the part.

Note 7: Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

Note 8: Limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.

Note 9: This parameter is guaranteed by design and/or characterization and is not tested in production.

Connection Diagrams

Ordering Information

Typical Performance Characteristics At T_J = 25°C, A_V = +1 (R_F = 0Ω), otherwise R_F = 560Ω for $A_V \neq +1$, unless otherwise specified.

Closed Loop Frequency Response for Various Supplies 3 $\overline{0}$ Ш -3 -6 GAIN (dB) -9 -12 -15 $A = +$ -18 $V_{\text{OUT}} = 0.2V$ $R_L = 1 k\Omega$ -21 10 100 1000 1 FREQUENCY (MHz)

Closed Loop Frequency Response for Various Supplies (Gain = +2)

Closed Loop Gain vs. Frequency for Various Temperatures

Large Signal Frequency Response

±0.1 dB Gain Flatness for Various Supplies

±0.1 dB Gain Flatness for Various Supplies

±0.1 dB Gain Flatness for Various Supplies

 0.3 3Ń 0.2 $5V$ 0.1 $\mathbf 0$ И -0.1 10V -0.2 GAIN (dB) -0.3 -0.4 -0.5 -0.6 -0.7 $A = +1$ -0.8 V_{OUT} = 2V -0.9 $R_L = 150\Omega$ -1 10 100 1000 1 FREQUENCY (MHz) 30033607 **Small Signal Frequency Response with Various Capacitive Load** \circ |CL $= 10 pF$ ϵ 'nF $C_{L} = 5.5$ pF 3 C_L $= 3.3$ pF (Bb) MIA_C $\mathbf 0$ HHII $= 2 pF$ Cı -3 $v^* = +2.5v$ -6 $\sqrt{ } = -2.5V$ $A = +1$ -9 $-V_{\text{OUT}} = 0.2V$ $R_L = 1 k\Omega$ -12 1 10 100 1000 FREQUENCY (MHz) 30033608 **HD2 and HD3 vs. Frequency and Supply Voltage** 0 $V_{\text{OUT}} = 2 V_{\text{PP}}$ -10 $R_L = 1 k\Omega$ ШI

±0.1 dB Gain Flatness for Various Supplies

±0.1 dB Gain Flatness for Various Supplies (Gain = +2)

Small Signal Frequency Response with Capacitive Load and Various R_{ISO}

HD2 and HD3 vs. Frequency and Load

HD3 vs. Frequency and Gain

30033652

HD2 vs. Output Swing

HD3 vs. Output Swing -10 $V^+ = +2.5V$ -20 $V = -2.5V$ 50 MHz -30 $-A = -1$ $-R_L = 1 k\Omega$ DISTORTION (dBc) -40 20 MHz -50 -60 10 MHz ×, -70 5 MHz -80 -90 ·2 MHz-∣ -100 1 MHz- -110 $\mathbf 0$ $\mathbf{1}$ $\mathbf 2$ 3 $\overline{\mathbf{4}}$ 5 VOUT (VPP) 30033683 **HD2 vs. Output Swing** -10 V^+ = +2.5V .50 MHz_ -20 $V = -2.5V$

Settling Time vs. Input Step Amplitude

CURRENT NOISE (PAV Hz)

1000

100

 10

 $10M$

30033668

30033658

 12

 $10\,$

Circuit for Negative (−) PSRR Measurement

+PSRR vs. Frequency

30033633

−PSRR vs. Frequency

Crosstalk vs. Frequency

30033611

Small Signal Step Response

Small Signal Step Response

Large Signal Step Response

Application Information

The LMH6611 and LMH6612 are based on National Semiconductor's proprietary VIP10 dielectrically isolated bipolar process. This device family architecture features the following:

- Complimentary bipolar devices with exceptionally high f_t (∼8 GHz) even under low supply voltage (2.7V) and low bias current.
- Common emitter push-push output stage. This architecture allows the output to reach within millivolts of either supply rail.
- Consistent performance with little variation from any supply voltage (2.7V - 11V) for the most important specifications (e.g. BW, SR, I_{OUT}.)
- Significant power saving compared to competitive devices on the market with similar performance.

With 3V supplies and a common mode input voltage range that extends beyond either supply rail, the LMH6611 is well suited to many low voltage/low power applications. Even with 3V supplies, the -3 dB BW (at $A_V = +1$) is typically 305 MHz.

The LMH6611 and LMH6612 are designed to avoid output phase reversal. With input overdrive, the output is kept near the supply rail (or as close to it as mandated by the closed loop gain setting and the input voltage). *Figure 1* shows the input and output voltage when the input voltage significantly exceeds the supply voltages.

FIGURE 1. Input and Output Shown with CMVR Exceeded

If the input voltage range is exceeded by more than a diode drop beyond either rail, the internal ESD protection diodes will start to conduct. The current flow in these ESD diodes should be externally limited.

SHUTDOWN CAPABILITY AND TURN ON/OFF BEHAVIOR

The LMH6611 can be shutdown by connecting the DISABLE pin to a voltage 0.5V below the supply midpoint which will reduce the supply current to typically 120 µA. The DISABLE pin is "active low" and can be connected through a resistor to V+ or left floating for normal operation. Shutdown is guaranteed when the DISABLE pin is 0.5V below the supply midpoint at any operating supply voltage and temperature. Typical turn on time is 20 ns and the turn off time is 60 ns.

In the shutdown mode, essentially all internal device biasing is turned off in order to minimize supply current flow and the output goes into high impedance mode. During shutdown, the input stage has an equivalent circuit as shown in *Figure 2*.

FIGURE 2. Input Equivalent Circuit During Shutdown

When the LMH6611 is shutdown, there may be current flow through the internal diodes shown, caused by input potential, if present. This current may flow through the external feedback resistor and result in an apparent output signal. In most shutdown applications the presence of this output is inconsequential. However, if the output is "forced" by another device, the other device will need to conduct the current described in order to maintain the output potential.

To keep the output at or near ground during shutdown when there is no other device to hold the output low, a switch using a transistor can be used to shunt the output to ground.

SELECTION OF R^F AND EFFECT ON STABILITY AND PEAKING

The peaking of the LMH6611 depends on the value of the R_F. From the graph shown in *Figure 3*, as the R_F value increases, the peaking increases.

For A_V = 2, at R_F = 1 kΩ, the -3 dB bandwidth is 113 MHz and peaking is about 0.6 dB whereas at R_F = 665 Ω , the -3 dB bandwidth is about 110 MHz and peaking is 0 dB. R_{F} and the input capacitance form a pole in the amplifier's response. If the time constant is too big, it will cause peaking and ringing. Except for A_V = 1 when R_F should be 0 Ω , across all other gain settings it is recommended that R_F remain between 500 Ω and 1 kΩ to ensure optimum performance.

FIGURE 3. Closed Loop Gain vs. Frequency and R^F = R^G

MINIMIZING NOISE

With a low input voltage noise of 10 nV/ \sqrt{Hz} and an input current noise of 2 $pA\sqrt{Hz}$ the LMH6611 and LMH6612 are suitable for high accuracy applications. Still being able to reduce the frequency band of operation of the various noise sources (i.e. op amp noise voltage, resistor thermal noise, input noise current) can further improve the noise performance of a system. In a non-inverting amplifier configuration inserting a capacitor, C_G , in series with the gain setting resistor, R_G , will reduce the gain of the circuit below frequency, $f =$ $1/2\pi R_G C_G$. This can be set to reduce the contribution of noise from the 1/f region. Alternatively applying a feedback capacitor, ${\sf C}_{\sf F}$, in parallel with the feedback resistor, ${\sf R}_{\sf F}$, will introduce a pole into your system at f = 1/2 π R_FC_F and create a low pass filter. This filter can be set to reduce high frequency noise and harmonics. Finally remember to keep resistor values as small as possible for a given application in order to reduce resistor thermal noise.

POWER SUPPLY BYPASS

Since the LMH6611 and LMH6612 are wide bandwidth amplifiers, proper power supply bypassing is critical for optimum performance. Improper power supply bypassing can result in large overshoot, ringing or oscillation. 0.1 μF capacitors should be connected from the supply pins, V+ and V−, to ground, as close to the device as is practical. Additionally, a 10 μF electrolytic capacitor should be connected from both supply pins to ground reasonably close to the device. Finally, near the device a 0.1 μF ceramic capacitor between the supplies will provide the best harmonic distortion performance.

INTERFACING HIGH PERFORMANCE OP AMPS WITH ADCs

These amplifiers are designed for ease of use in a wide range of applications requiring high speed, low supply current, low noise, and the ability to drive complex ADC and video loads. The source that drives the modern high resolution analog-todigital converters (ADCs) sees a high frequency AC load and a DC load of a few hundred ohms or more. Thus, a high performance op amp with high input impedance of a few mega ohms and low output impedance would be an ideal choice as an input ADC driver. The LMH6611/LMH6612 have the low output impedance of 0.07 Ω at f = 1 MHz. The ADC driver acts as a buffer and a low pass filter to reduce the overall system noise. To utilize the full dynamic range of the ADC, the ADC input has to be driven to full scale input voltage.

As signals travel through the traces of a printed circuit board (PCB) and long cables, system noise accumulates in the signals and a differential ADC rejects any signals noise that appears as a common mode voltage. There are a couple of advantages to using differential signals rather than singleended signals. First, differential signals double the dynamic range of the ADC and second, they offer better harmonic distortion performance. There are several ways to produce differential signals from a dual op amp configuration. One method is to utilize the single-ended to differential conversion technique and the other is the differential to differential conversion technique. The first method requires a single input source and the second method requires differential input source.

A real world input source can have non-ideal impedance thus the buffer amplifier, with very low output impedance, is required to drive the input of the ADC. To minimize the droop in the input voltage, external shunt capacitance (C_{L}) should be about ten times larger than the internal input capacitance of the ADC and external series resistance $\sf(R_L)$ should be large enough to maintain the phase delay at the output of the op amp and hence maintain the stability (See *[Figure 4](#page-22-0)*) . Most applications benefit from the inclusion of a series isolation resistor connected between the op amp output and ADC input. This series resistor helps to limit the output current of the op amp. The value chosen for this series resistor is very important, as a higher value will increase the load impedance seen by the op amp and improve the total harmonic distortion (THD) performance of the op amp; however, the ADC prefers a low impedance source driving it. Thus, the optimum value for this series resistor must be found so that it will offer the best performance in terms of THD, SNR and SFDR of the combined op amp and ADC.

Important Specifications of Op Amp and ADC

When interfacing an ADC with an op amp it is imperative to understand the specifications that are important to get the expected performance results. Modern ADC AC specifications such as THD, SNR, settling time and SFDR are critical for filtering, test and measurement, video and reconstruction applications. The high performance op amp's settling time, THD, and noise performance must be better than that of the ADC it is driving to maintain the proper system accuracy with minimal or no error.

Some system applications require low THD, low SFDR and wide dynamic range (SNR), whereas some system applications require high SNR and they may sacrifice THD and SFDR to focus on the noise performance.

Noise is a very important specification for both the op amp and the ADC. There are three main sources of noise that contribute to the overall performance of the ADC: Quantization noise, noise generated by the ADC itself (particularly at higher frequencies) and the noise generated by the application circuit. The impedance of the input source affects the noise performance of the op amp. Theoretically, an ADC's signal to noise ratio (SNR) can be found from the equation:

SNR (in dB) = 6.02*N+1.72

where N is the resolution of the ADC. For example, according to this equation a 12-bit ADC has an SNR of 74 dB. However, the practical SNR number would be about 72 dB. In order to achieve better SNR, the ADC driver noise should be as small as possible. The LMH6611/LMH6612 have the low voltage noise of only 10 nV/\sqrt{Hz} .

The combined settling time of the op amp and the ADC must be within 1 LSB. The 0.01% settling time of the LMH6611/ LMH6612 is 100 ns.

The ADC driver's THD should be inherently lower than that of the ADC. The LMH6611/LMH6612 have an SFDR of 96 dBc at 2 V_{PP} output and 1 MHz input frequency.

Signal to Noise and Distortion (SINAD) is a parameter which is the combination of the SNR and THD specifications. SINAD is defined as the RMS value of the output signal to the RMS value of all of the other spectral components below half the clock frequency, including harmonics but excluding DC. It can be calculated from SNR and THD according to the equation:

SINAD = 20 * LOG
$$
\sqrt{10^{10} + 10^{10}}
$$

LMH6611/LMH6612 **LMH6611/LMH6612**

Because SINAD compares all undesired frequency components with the input frequency, it is an overall measure of an ADC's dynamic performance. The following sections will discuss the three different ADC driver architectures in detail.

SINGLE TO SINGLE ADC DRIVER

This architecture has a single-ended input source connected to the input of the op amp and the single-ended output of the op amp is then fed to the single-ended input of the ADC. The low noise of only 10 nV/ \sqrt{Hz} and a wide bandwidth of 345 MHz make the LMH6611 an excellent choice for driving the 12-bit ADC121S101 500 KSPS to 1 MSPS ADC, which has a successive approximation architecture with internal sample and hold circuits. *[Figure 2](#page-20-0)* shows the schematic of the LMH6611 in a 2nd order multiple-feedback with gain of −1 (inverting) configuration, driving an ADC121S101. The inverting configuration is preferred over the non-inverting configuration, as it offers more linear output response. *Table 1* shows the performance data of the LMH6611 combined with the AD-C121S101. The ADC driver's cutoff frequency of 500 kHz is found from the equation:

$$
f_0 = \frac{1}{2\pi} \times \sqrt{\frac{1}{R_2 \times R_5 \times C_2 \times C_5}}
$$

The op amp's gain is set by the equation:

$$
GAIN = -\frac{R_2}{R_1}
$$

FIGURE 4. Single to Single ADC Driver

Amplifier	SINAD	SNR	THD	SFDR	ENOB	Notes
Output/ADC Input	(dB)	(dB)	(dB)	(dBc)		
	70.2	71.6	-75.7	77.6	11.4	$ADC121S101 @ f = 200 kHz$

TABLE 1. Performance of the LMH6611 Combined with the ADC121S101

When the op amp and the ADC are using the same supply, it is important that both devices are well bypassed. A 0.1 μ F ceramic capacitor and a 10 µF tantalum capacitor should be located as close as possible to each supply pin. A sample layout is shown in *[Figure 5](#page-23-0)*. The 0.1 µF capacitors (C13 and C6) and the 10 µF capacitors (C11 and C5) are located very close to the supply pins of the LMH6611 and the AD-C121S101.

The following are recommendations for the design of PCB layout in order to obtain the optimum high frequency performance:

- Place ADC and amplifier as close together as possible.
- Put the supply bypassing capacitors as close as possible to the device $(<1")$.
- Utilize surface mount instead of through-hole components and ground and power planes.
- Keep the traces short where possible.
- Use terminated transmission lines for long traces.

FIGURE 5. LMH6611 and ADC121S101 Layout

SINGLE-ENDED TO DIFFERENTIAL ADC DRIVER

The single-ended to differential ADC driver in Figure 3 utilizes an LMH6612 dual op amp to buffer a single-ended source to drive an ADC with differential inputs. One of the op amps is configured as a unity gain buffer that drives the inverting (IN−) input of the op amp U2 and non-inverting (IN+) input of the ADC121S625. U2 inverts the input signal and drives the inverting input of the ADC121S625. The ADC driver is configured for a gain of +2 to reduce the noise without sacrificing THD performance. The common mode voltage of 2.5V is set

up at the non-inverting inputs of both op amps U1 and U2. This configuration produces differential ± 2.5 V_{PP} output signals, when the single-ended input signal of 0 to V_{REF} is AC coupled into the non-inverting terminal of the op amp and each non-inverting terminal of the op amp is biased at the midscale of 2.5V. The two output RC anti-aliasing filters are used between both the outputs of U1 and U2 and the input of the ADC121S625 to minimize the effect of undesired high frequency noise coming from the input source. Each RC filter has the cutoff frequency of approximately 22 MHz.

The performance of the LMH6612 with the ADC121S625 is shown in *Table 2*.

TABLE 2. Performance of the LMH6612 Combined with the ADC121S625

DIFFERENTIAL TO DIFFERENTIAL ADC DRIVER

The LMH6612 dual op amp can be configured as a differential to differential ADC driver to buffer a differential source to a differential input ADC as shown in *Figure 7*. The differential to differential ADC driver can be formed using two single to single ADC drivers. Each output from these drivers goes to a separate input of the differential ADC. Here, each single to single ADC driver uses the same components and is configured for a gain of -1 (inverting).

FIGURE 7. Differential to Differential ADC Driver

The following table summarizes the performance of the LMH6612 combined with the ADC121S625 at two different frequencies. In order to utilize the full dynamic range of the

ADC, the maximum input of 2.5 V_{PP} is applied to the ADC input. *Figure 8* shows the FFT plot of the LMH6612 and AD-C121S625 combination tested at f = 20 kHz input frequency.

FIGURE 8. The FFT Plot of Differential to Differential ADC Driver

DC LEVEL SHIFTING

Often a signal must be both amplified and level shifted while using a single supply for the op amp. The circuit in *Figure 9* can do both of these tasks. The procedure for specifying the resistor values is as follows.

- 1. Determine the input voltage.
- 2. Calculate the input voltage midpoint, $V_{INMID} = V_{INMIN} +$ $(V_{INMAX} - V_{INMIN})/2$.
- 3. Determine the output voltage needed.
- 4. Calculate the output voltage midpoint, $V_{\text{OUTMID}} =$ $V_{OUTMIN} + (V_{OUTMAX} - V_{OUTMIN})/2.$
- 5. Calculate the gain needed, gain = $(V_{\text{OUTMAX}} V_{\text{OUTMIN}})$ $(V_{INMAX} - V_{INMIN})$
- 6. Calculate the amount the voltage needs to be shifted from input to output, $\Delta V_{\text{OUT}} = V_{\text{OUTMID}} -$ gain x V_{INMID} .
- 7. Set the supply voltage to be used.
- 8. Calculate the noise gain, noise gain = gain + $\Delta V_{\text{OUT}}/V_{\text{S}}$.
- 9. Set R_F.
- 10. Calculate R_1 , $R_1 = R_F / g$ ain.
- 11. Calculate R_2 , $R_2 = R_F/(noise gain-gain)$.
- 12. Calculate R_G , $R_G = R_F / (n \text{oise gain} 1)$.

Check that both the V_{IN} and V_{OUT} are within the voltage ranges of the LMH6611.

FIGURE 9. DC Level Shifting

The following example is for a V_{IN} of 0V to 1V with a V_{OUT} of 2V to 4V.

- 1. $V_{IN} = 0V$ to 1V
- 2. $V_{INMID} = 0V + (1V 0V)/2 = 0.5V$
- 3. $V_{OIII} = 2V$ to 4V
- 4. $V_{\text{OUTMID}} = 2V + (4V 2V)/2 = 3V$
- 5. Gain = $(4V 2V)/(1V 0V) = 2$
- 6. $\Delta V_{\text{OUT}} = 3V 2 \times 0.5V = 2$
- 7. For the example the supply voltage will be +5V.
- 8. Noise gain = $2 + 2/5V = 2.4$
- 9. $R_F = 2 k\Omega$
- 10. $R_1 = 2 kΩ/2 = 1 kΩ$
- 11. $R_2 = 2 k\Omega/(2.4-2) = 5 k\Omega$
- 12. $R_G = 2 kΩ/(2.4 1) = 1.43 kΩ$

4th ORDER MULTIPLE FEEDBACK LOW-PASS FILTER

Figure 10 shows the LMH6612 used as the amplifier in a multiple feedback low pass filter. This filter is set up to have a gain of +1 and a −3 dB point of 1 MHz. Values can be determined by using the WEBENCH® Active Filter Designer found at www.amplifiers.national.com.

FIGURE 10. 4th Order Multiple Feedback Low-Pass Filter

CURRENT SENSE AMPLIFIER AND OPTIMIZING ACCURACY IN PRECESION APPLICATIONS

With it's rail-to-rail output capability, low V_{OS} , and low I_{B} the LMH6611 is an ideal choice for a current sense amplifier application. *Figure 11* shows the schematic of the LMH6611 set up in a low-side sense configuration which provides a conversion gain of 2V/A. Voltage error due to V_{OS} can be calculated to be $\rm V_{OS}$ x (1 + $\rm R_{F}/R_{G}$) or 0.6 mV x 21 = 12.6 mV. Voltage error due to I_O is I_O x R_F or 0.5 µA x 1 kΩ = 0.5 mV. Hence worst case total voltage error is 12.6 mV + 0.5 mV or 13.1 mV which translates into a current error of 13.1 mV/(2 V/ A) = 6.55 mA.

This circuit employs DC source resistance matching at the two input terminals in order to minimize the output DC error caused by input bias current. Another technique to reduce output offset in a non-inverting amplifier configuration is to introduce a DC offset current into the inverting input of the amplifier. To ensure minimal impact on frequency response be sure to inject the DC offset current through large resistors. Conversely if optimizing an inverting amplifier configuration simply apply offset adjustment to the non-inverting input.

FIGURE 11. Current Sense Amplifier

TRANSIMPEDANCE AMPLIFIER

By definition, a photodiode produces either a current or voltage output from exposure to a light source. A Transimpedance Amplifier (TIA) is utilized to convert this low-level current to a usable voltage signal. The TIA often will need to be compensated to insure proper operation.

FIGURE 12. Photodiode Modeled with Capacitance Elements

Figure 12 shows the LMH6611 modeled with photodiode and the internal op amp capacitances. The LMH6611 allows circuit operation of a low intensity light due to its low input bias

current by using larger values of gain (R_F) . The total capacitance (C_T) on the inverting terminal of the op amp includes the photodiode capacitance (C_{PD}) and the input capacitance of the op amp (C_{IN}) . This total capacitance (C_{T}) plays an important role in the stability of the circuit. The noise gain of this circuit determines the stability and is defined by:

$$
NG = \frac{1 + sR_F (C_T + C_F)}{1 + sC_F R_F}
$$
 (1)

Where,
$$
f_z \approx \frac{1}{2\pi R_F C_T}
$$
 and $f_P = \frac{1}{2\pi R_F C_F}$ (2)

FIGURE 13. Bode Plot of Noise Gain Intersecting with Op Amp Open Loop Gain

Figure 13 shows the bode plot of the noise gain intersecting the op amp open loop gain. With larger values of gain, ${\mathsf C}_{{\mathsf T}}$ and R_F create a zero in the transfer function. At higher frequencies the circuit can become unstable due to excess phase shift around the loop.

A pole at f_P in the noise gain function is created by placing a feedback capacitor (C_{F}) across R_{F} . The noise gain slope is flattened by choosing an appropriate value of C_F for optimum performance.

Theoretical expressions for calculating the optimum value of C_F and the expected -3 dB bandwidth are:

$$
C_F = \sqrt{\frac{C_T}{2\pi R_F(GBWP)}}
$$
\n(3)

$$
f_{3 dB} = \sqrt{\frac{GBWP}{2\pi R_F C_T}}
$$
 (4)

Equation 4 indicates that the −3 dB bandwidth of the TIA is inversely proportional to the feedback resistor. Therefore, if the bandwidth is important then the best approach would be to have a moderate transimpedance gain stage followed by a broadband voltage gain stage.

[Table 4](#page-28-0) shows the measurement results of the LMH6611 with different photodiodes having various capacitances (C_{PD}) and a feedback resistance $(\mathsf{R}_{\mathsf{F}})$ of 1 k Ω .

TABLE 4. TIA (*[Figure 1](#page-20-0)***) Compensation and Performance Results**

Note:

GBWP = 130 MHz $C_T = C_{PD} + C_{IN}$

 $C_{IN} = 2 pF$

 $\rm V_{\rm S}$ = $\pm 2.5 \rm V$

Figure 14 shows the frequency response for the various photodiodes in *Table 4*.

FIGURE 14. Frequency Response for Various Photodiode and Feedback Capacitors

When analyzing the noise at the output of the TIA, it is important to note that the various noise sources (i.e. op amp noise voltage, feedback resistor thermal noise, input noise current, photodiode noise current) do not all operate over the same frequency band. Therefore, when the noise at the output is calculated, this should be taken into account. The op amp noise voltage will be gained up in the region between the noise gain's zero and pole (f_Z and f_P in *[Figure 13](#page-27-0)*). The higher the values of R_{F} and C_{T} , the sooner the noise gain peaking starts and therefore its contribution to the total output noise will be larger. It is advantageous to minimize C_{IN} by proper choice of op amp or by applying a reverse bias across the diode but this will be at the expense of excess dark current and noise.

EVALUATION BOARD

National Semiconductor provides the following evaluation board as a guide for high frequency layout and as an aid in device testing and characterization. Many of the datasheet plots were measured with this board:

This evaluation board can be shipped when a device sample request is placed with National Semiconductor.

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